MN1380 Series **CMOS LSIs for Voltage Detection**

Overview

The MN1380 series are elements that monitor the power supply voltage supplied to microcomputers and other LSI systems and issue reset signals for initializing the system after the power is first applied or for preventing runaway operation when the supply voltage fluctuates.

There is a choice of three output types: CMOS output, N-channel open drain output, and inverted CMOS output. There are also three package types: M, TO-92, and a mini type for surface mounting.

Choose the ideal element for your application from the series' wide selection of detection ranks (17 ranks between 2.0 and 4.9 volts), output types, and package types.

Features

- Three-pin element requiring no adjustment
- Wide selection of detection ranks (17 ranks between 2.0 and 4.9 volts)
- Highly precise detection voltage
- Detection voltage with hysteresis characteristic $\Delta VD = 50 \text{ mV}$ for ranks C to K $\Delta VD = 100 \text{ mV}$ for ranks L to U
- Low current consumption: $I_{DD} = 1\mu A$ (typ.) for V_{DD} = 5 V
- Low fluctuation in detection voltage with tempera-

- Microcomputer reset circuits
- Reset circuits for other electronic circuits

Pin Assignment



MN1380 Series Naming Conventions

The MN1380 series offers a wide selection of detection ranks, output types, package types, and packaging. All combinations use the following naming conventions. When ordering, be sure to give the correct part number using these naming conventions.



Minimum Packaging Unit

Bulk (M and TO-92 types) 1,000 Magazine (Mini type) 50 Taping (Mini and TO-92 types) 3,000

Series Lineup

Output Package	M type Package	TO-92 type Package	Mini type Package
CMOS output	MN1380	MN1381	MN1382
N-channel open drain output	MN13801	MN13811	MN13821
Inverted CMOS output	MN13802	MN13812	MN13822

Detection Ranks (on Voltage)



Block Diagram



Note *1: Circuits vary slightly depending on the output type (CMOS output, N-channel open drain output, or inverted CMOS mation output)

Pin Descriptions

Pin No.	Symbol	Function Description
1	OUT	Reset signal output pin
2	V _{DD}	Power supply pin
3	V _{SS}	Ground pin
		Reset signal output pin Power supply pin Ground pin Ground pin Alborn Alb

■ Absolute Maximum Ratings V_{SS}=0V, Ta=25°C

Parameter	Symbol	Rating	Unit
Power supply voltage	V _{DD}	7.0	V
Output voltage	Vo	-0.3 to V _{DD} +0.3	V
Operating ambient temperature	Та	-20 to +70	°C
Storage temperature	T _{stg}	-55 to +125	°C

■ Recommended Operating Conditions V_{ss}=0V, Ta=25°C

Parameter	Symbol	Conditions	min	typ	max	Unit
Power supply voltage	V _{DD}	See Figures 1 and 4.	1.5	C	6.0	V

Electrical Characteristics

Parameter	Symbol	Conditi	ons	min	typ	max	Unit
Power supply current	I _{DD}	V _{DD} = 5 V ^{*1} Load resistance =	= 10 kW		Y	5	γµA
Detection voltage for drop in power supply voltage *2	V _{DL}	Ta=25°C		*2		- main	V
Detection voltage hysteresis width *2	ΔVD	See Figures 1 and	d 4.	*2	X ⁱ S	*2	mV
"H" level output voltage	V _{OH}	Inverted V	_{DH} =- 40μA _{DD} =1.8V _{DH} =- 0.5mA	0.8V _{DD}	iscle	V _{DD} V _{DD} -1.5	V
"L" level output voltage	V _{OL}	drain output I _C Inverted V CMOS output I _C	DD=1.8V DL=0.7mA DD=6.0V DH=0.3mA	V _{SS}	,> 	0.4	v
lotes 1. This includes the output pin's 2: For particulars, see the detect	leakage cu on voltage	rrent. rank table, ollow visit ht	in Parice				

Electrical Characteristics (continued)

2) AC Characteristics V_{SS}=0V, Ta=25°C



Description of Operation



Notes

- 1: Output cannot be specified for power supply voltages under 1.5 V because operation is not guaranteed for that range.
- 2: V_{DL}: Detection voltage for dropin power supply voltage

V_{DH}: Detection voltage for rise in power supply voltage

- t_{OL} : Time lag between the time that the power supply voltage reaches the detection voltage (V_{DL} or V_{DH}) and the time that the output pin (OUT) goes to "L" level.
- t_{OH} : Time lag between the time that the power supply voltage reaches the detection voltage (V_{DL} or V_{DH}) and the time that the output pin (OUT) goes to "H" level.
- 3: These characteristics for the N-channel open drain output are when a load resistor is connected between the OUT and V_{DD} pins.

Description for Measuring the Output Characteristics





Description for Measuring the I/O Characteristics



Figure 4. Description chart for Measuring the I/O Characteristics

Notes

1: Output cannot be specified for power supply voltages under 1.5 V because operation is not guaranteed for that range.

2: V_{DL} : Detection voltage for drop in power supply voltage

V_{DH}: Detection voltage for rise in power supply voltage

3: These characteristics for the N-channel open drain output are when a load resistor is connected between the OUT and V_{DD} pins.

Application Circuit Example

Connect resistors, capacitors, and the like only to the output pin on the MN1380 series element. Note that connecting them to the Power source pins changes V_{DH} , V_{DL} , and ΔVD .



Package Dimensions (Unit: mm)

M type package



Note) The package will be changed to lead-free type (M3A). See the new package dimensions section later of this datasheet.

Package Dimensions (Unit: mm)(continued)

TO-92 type package



Package Dimensions (Unit: mm)(continued)

Mini type package



Note) The package will be changed to lead-free type (MINI-3DC). See the new package dimensions section later of this datasheet.

Reference Characteristics

The following characteristics curves represent results from a specific sample therefore they do not guarantee the characteristics for the final product.



Figure 6.a. I_{DD} Temperature Characteristic (Rank Q)

Figure 6.b. Measurement Circuit



Reference Characteristics (continued)



Figure 8.b. Measurement Circuit

Reference Characteristics (continued)



Figure 10.a. I_{OH} vs. V_{OH} Characteristic

Figure 10.b. Measurement Circuit





Figure 12.a. I_{OH} vs. Temperature Characteristic

Figure 12.b. Measurement Circuit

W

■ TO-92 Type Package Taping-Specifications (MN1381/MN13811/MN13812)



Figure 13. TO-92 Type Package Taping-Dimensions (Ammunition pack)

10-92 Type I ackage		ins (Annihumunition)	Jack)	(O)	
Name	Symbol	Length (mm)	Name	Symbol	Length (mm)
Product height*	А	5.3 max	Adhesive tape width	W0	6.0±0.5
Product width*	A1	5.2 max	Feed hole position	W1	9.0±0.5
Product thickness*	* T	4.2 max	Adhesive tape position	w2	0.5 max
Lead width*	d	$0.45^{+0.15}_{-0.1}$	Distance to top of product	J S H	25.0 max
Taped lead length	/1	2.0 max	Distance to	HO	10.010.5
Product pitch	Р	12.7±1.0	bottom of product	HU	19.0±0.5
Feed hole pitch	P0	12.7±0.3	Lead clinch height	H1	16.0±0.5
Feed hole position	n P1	6.35±0.5	Feed hole diameter	D0	4.0±0.2
Lead spacing	F1, F2	2.5 +0.5 -0.2	Tape thickness	t1	0.7±0.2
Product deflection ang	gle $\Delta h l, \Delta h 2$	2.0 max	Total tape thickness	t2	1.5 max
Tape width	W	$18.0^{+1.0}_{-0.5}$	~0.		
		5° VISIT Y	Note*1: For further details,	25 element	s (example)
W	Н	D	Leave the space for least three elements	at	
330	250	41	icast unce elements	REFERENCE	
		Unit: mm	ر س		B

TO-92 Type Package Taping Dimensions (Ammunition pack)

Figure 14. Box Dimensions for TO-92 Type Packages with Ammunition pack

Embossed Taping Specifications for Mini Type Package (MN1382/MN13821/MN13822)

There is a choice of two orientations, TW and TX, for the product relative to the tape.



Figure 18. Embossed Taping Reel Dimensions for Mini Type Package

Reliability Testing Results for MN1380 Series

(1) M type package (MN1380/MN13801/MN13802) and TO-92 type package (MN1381/MN13811/MN13812)

Test Subjects	Test Conditions	Results
Operating lifetime test	V _{DD} =5.5V, Ta=125°C, t=1000hrs	0/15
High-temperature storage test	Ta=150°C, t=1000hrs	0/15
Low-temperature storage test	Ta=-65°C, t=1000hrs	0/15
High-temperature,	Ta=85°C, RH=85%, t=1000hrs	0/15
high-humidity storage test		
High-temperature,	V _{DD} =5.5V, Ta=85°C, RH=85%, t=1000hrs	0/15
high-humidity bias test		
Thermal shock test	Ta=150°C and –65°C.	0/15
	Five minutes at each temperature for ten cycles	
Temperature cycle test	Ta=150°C and -65°C.	0/15
	Thirty minutes at each temperature for ten cycles	
Pressure cooker test	Two atmospheres for 50 hours at ambient temperature (Ta) of 121°C	0/15
Soldering test	Ambient temperature (Ta) of 230°C for five seconds	0/15
Solder heat resistance test	Ambient temperature (Ta) of 270°C for ten seconds	0/15
Mini type package (MN1382/M	N13821/MN13822)	N.
Test Subjects	Test Conditions	Results
Operating lifetime test	V _{DD} =5.5V, Ta=125°C, t=1000hrs	0/15
High-temperature storage test	Ta=150°C, t=1000hrs	0/15
Low-temperature storage test	Ta=150°C, t=1000hrs Ta=-65°C, t=1000hrs Ta=85°C, RH=85%, t=1000hrs	0/15
High-temperature,	Ta=85°C, RH=85%, t=1000hrs	0/15
high-humidity storage test	JUL 1/50	
High-temperature,	V _{DD} =5.5V, Ta=85°C, RH=85%, t=1000hrs	0/15
high-humidity bias test		
Thermal shock test	Ta=150°C and -65°C.	0/15
	Five minutes at each temperature for ten cycles	
Temperature cycle test	Ta=150°C and -65°C	0/15
	Thirty minutes at each temperature for ten cycles	
Pressure cooker test *1	Two atmospheres for 24 hours at ambient temperature (Ta) of 121°C	0/15
Soldering test	Ambient temperature (Ta) of 230°C for five seconds	0/15

Note*1: Note that the testing conditions for the mini package differ from those for the other two packages.

- New Package Dimensions (Unit: mm)
- M3A (Lead-free package)



- New Package Dimensions (Unit: mm)(continued)
- SSIP003-P-0000S (Lead-free package)



- New Package Dimensions (Unit: mm)(continued)
- MINI-3DC (Lead-free package)



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